

# Cu-Ag binary system revised: wettability, surface composition, thermodynamics of phase boundaries

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Interfacial thermodynamics and capillary phenomena in binary Ag-Cu system are of special interest from both practical and theoretical point of view. On the one hand this system is a base for lead free solders in modern micro- and nanotechnologies. On the other hand due to the absence of intermetallic compounds in the Ag-Cu system and low affinity of both components to oxygen it provides a good model for studying the influence of the second component on the interfacial thermodynamics. It has been recently confirmed that the surface tension of liquid Ag-Cu alloy is well described by the Buttler equation [1] and there is noticeable enrichment of the alloy surface with silver. Similar trend was observed for the single phase solid solution of Ag in Cu: the solid-gas surface energy decreases with the increase of Ag content [2] and enrichment of the alloy surface with Ag was detected by AES [3].

The aim of the present study is to analyze the surface composition and thermodynamics of the single phase solid solution of Cu in Ag. The surface tension of solid Ag-xCu alloys, where x varies from 0.41 to 7.95 at. %, was measured by zero-creep method. Growth of the surface tension with Cu content was detected. XPS studies revealed the depletion of the surface with copper relative to the bulk composition: 1.5 at. % of Cu was detected on the surface of Ag-2.2at.%Cu solid solution. At the same time the formation of copper-rich nanoparticles was detected by SEM on the surface of Ag-7.95at.%Cu solid solution. Wettability of pure Ag and Ag-Cu solid solution by Cu-Ag melt is analyzed taking into account the diffusion of copper from liquid phase into the substrate and morphology of Cu-rich particles on the Ag surface.

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